

Low-Power, High-Resolution Pressure Sensor

Features

- Supply voltage: 1.8V ~ 3.6V
- Package: SOIC-16
 Footprint: 10.3 × 10.3mm
 Height: 10.3mm
- Supply voltage: 1.8V to 3.6V
- Relative accuracy: ±0.03hPa(±0.25m)
 Absolute accuracy: Typ.±1.5hPa
- Integrated digital pressure sensor (24 bit ΔΣ ADC)
- SPI / I2C serial interface
- Current consumption: 3.5µA @1Hz
- Operating range: 300 to 1200 hPa, -20 to +85 °C
- RoHs compliant, halogen-free

Applications

- Barometer and altimeter for portableDevices
- Indoor and outdoor navigation
- Weather station equipment
- Multisport watches
- Drones and other autonomous vehicles
- Fitness trackers

Tecnical advantages

- Wide temperature:-20~+85°C
- Small package, height only 3.3mm
- Excellent performance and cost

Brief Description

- WF200D is a high precision barometer timeter especially designed for consumer applications. It measures the pressure based on piezo-resistive MEMS pressure sensor.
- Optimized for ultra-low power and low voltage for use in mobile phones, smart watches,PDAs, GPS navigation devices and outdoor equipment.
- The sensor module is housed in a compact 16-pin SOIC package with a footprint of only 10.3 × 10.3 mm and 10.3 mm package height. Its small dimensions and its low power consumption allow the implementation in battery driven devices. With a low altitude noise of merely 0.08m and very low offset temperature coefficient(TCO), the offers superior performance and cost are perfectly suitable for applications like flying toys and sport watches.
- The IIC/SPI interface allows for easy system integration with a microcontroller.



PREFORMANCE SPECIFCIATIONS

• ABSOLUTE MAXIMUM RATINGS (VDD = 3.3V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Supply voltage	Vdd		-0.3		+4	V
Storage temperature	Ts		-40		+85	°C
Overpressure	P _{max}	ISO 22810			10	bar
Maximum Soldering	Tmax	40 sec. max			260	°C
Temperature						
ESD rating		Human Body Model	-2		+2	kV

• ELECTRICAL CHARACTERISTICS (VDD = 3.3V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Conc	Condition		Тур.	Max	Unit
Operating Supply voltage	Vdd			1.8	3.3	3.6	V
Operating Temperature	Т			-20	+25	+85	°C
Peak supply current		during co	onversion		1.25		mA
			8192		21.09		
			4096		11.05		
Supply current	ldd	OSR	2048		6.02		μA
(1 sample per sec.)			1024		3.51		
			512		2.26		
			256		1.63		
Standby supply current		at 25°C (V	at 25°C (V _{DD} = 3.3 V)		0.01	0.1	μA
VDD Capacitor		from VDI	D to GND	100	470		nF



I2C INTERFACE

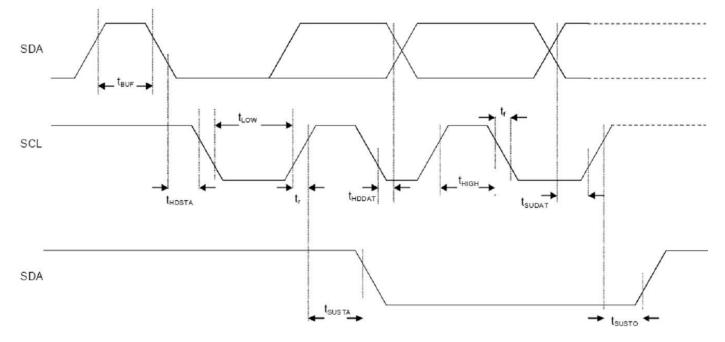
I2C bus uses SCL and SDA as signal lines. Both lines are connected to VDDIO externally via pull-up resistors so that they are pulled high when the bus is free. The I2C device address of is shown below. The LSB bit of the 7bits device address is configured via SDO/ADDR pin.

IIC Device Address

		Device Address											
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0					
Default	1	1	0	1	1	0	1	0/1					
Custom	1	1	0	1	1	0	SDO/ADDR	0/1					

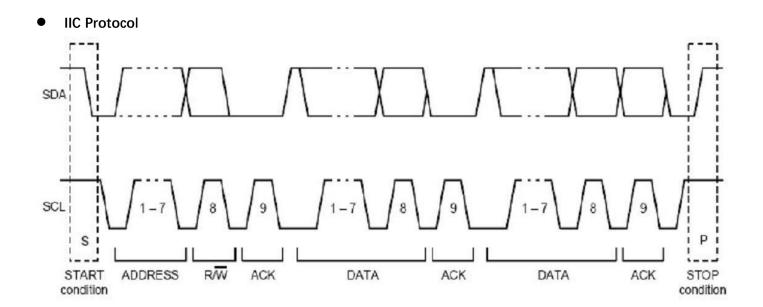
• Electrical specification of the I2C interface pins

Symbol	Parameter	Min	Max	Unit
fscl	Clock frequency		400	kHz
t low	SCL low pulse	1.3		μs
tніgн	SCL high pulse	0.6		μs
t sudat	SDA setup time	0.1		μs
t hddat	SDA hold time	0.0		μs
t susta	Setup Time for a repeated start condition	0.6		μs
t hdsta	Hold time for a start condition	0.6		μs
t susto	Setup Time for a stop condition	0.6		μs
t buf	Time before a new transmission can start	1.3		μs



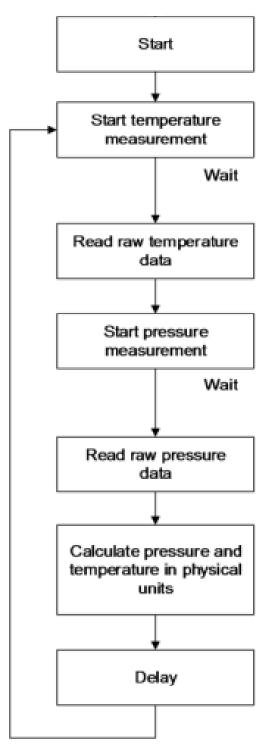


The I2C interface protocol has special bus signal conditions. Start (S), stop (P) and binary data conditions are shown below. At start condition, SCL is high and SDA has a falling edge. Then the slave address is sent. After the 7 address bits, the direction control bit R/W selects the read or write operation. When a slave device recognizes that it is being addressed, it should acknowledge by pulling SDA low in the ninth SCL (ACK) cycle. At stop condition, SCL is also high, but SDA has a rising edge. Data must be held stable at SDA when SCL is high. Data can change value at SDA only when SCL is low.



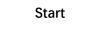


PRESSURE AND TEMPERATURE CALCULATIO





Low-Power, High-Resolution Pressure Sensor



TMIN=-40°C TMAX=85°C TREF=25°C

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Read digital pressure and temperature data											
Reg		Description	R/W	Default							
0x30	CMD	Measurement_control<3:0>: 1000b, indicate a single shot temperature signalconversion. 1001b, indicate a single shot sensor signal conversion. 1010b: indicate a combined conversion (once temperature conversion immediately followed by once sensor signal conversion).	RW	0x00							
0x06	PRESSURE_MSB	Data out<23:16>	R	0x00							
0x07	PRESSURE _CSB	Data out<15:8>	R	0x00							
0x08	PRESSURE _LSB	Data out<7:0>	R	0x00							
0x09	TEMP_MSB	Temp out<15:8>	R	0x00							
0x0A	TEMP_LSB	Temp out<7:0>	R	0x00							

*Reg0x09-Reg0x0A: Temperature output with an LSB

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Calculate										
	Size [bit]	Zero Condition	Below Zero	Above Zero						
PRESSURE	24	8388608	=((PRESSURE_MSB <<16) & (PRESSURE _CSB<<8) && PRESSURE _LSB)/ 8388608	=(((PRESSURE_MSB <<16) & (PRESSURE _CSB<<8) && PRESSURE _LSB)- 16777216)/ 8388608						
TEMP	16	32768	=((TEMP_MSB<<8) & TEMP_LSB)/256	=(((TEMP_MSB<<8) & TEMP_LSB) - 65536)/256						
* PRESSURE:	* PRESSURE: It also needs to be converted according to the pressure range, Using the driver C code is strongly									

recommended. Please contact with WFH for details.



Pressure Sensor

• IIC timing diagram										
From master to slave			S Start	S Start			A Acknowledge			
From slave to master			P Stop			N Not Ack	nowl	edge		
Write Data (IIC Write)										
S DeviceAddress	W	Α	Command	Α	Ρ					
S DeviceAddress	W	Α	Command	Α		Value	Α	Ρ		
(a) temperature conversion										
S DeviceAddress	W	Α	0x30	Α		0x08	Α	Ρ		
(b) pressure conversion command										
S DeviceAddress	W	A	0x30	Α		0x09	Α	Ρ		

Read Data (IIC Read)

(a) After sending the temperature conversion command, read 16bit data from the output buffer

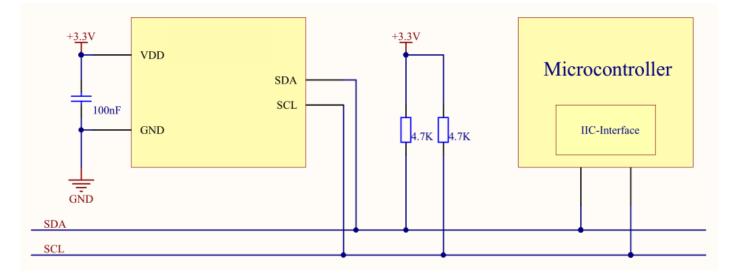
S	DeviceAddress	W	Α	0x09	Α			
S	DeviceAddress	R	Α	TEMP_MSB	Α	TEMP_LSB	Ν	Ρ

(b) After sending the pressure conversion command, read 24bit data from the output buffer

S	DeviceAddress	W	Α	0x06	Α				
S	DeviceAddress	R	Α	PRESSURE_MSB	Α	PRESSURE_CSB	Α	PRESSURE_LSB	NP

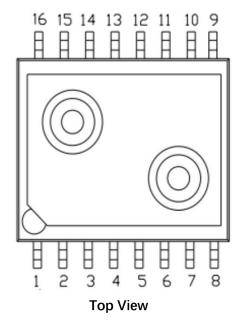


APPLICATION CIRCUIT



PIN CONFIGURATION AND DEVICE PACKAGE OUTLINE

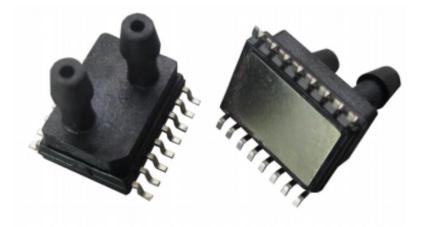
• Package Information



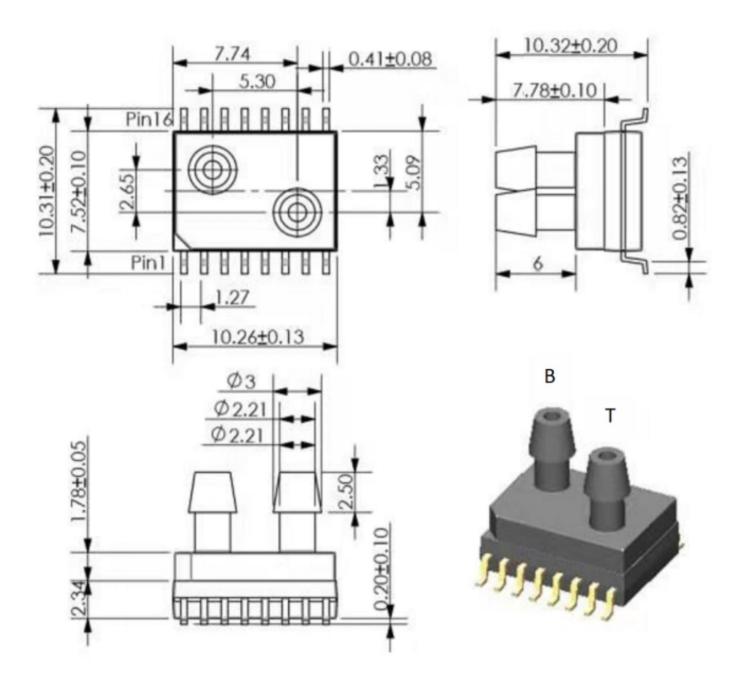
Pin	Name	Function
1		
2		
3		
4		
5	VDD	Positive supply voltage
6	INT	Data ready
7	CSB	Chip select
8		
9		
10	SDA	Serial data
11	SCL	Serial data clock
12	SDO	Address select in I2C mode
13	GND	Ground
14		
15		
16		



• Pin Configuration (Notes: Mechanical dimension is mm)

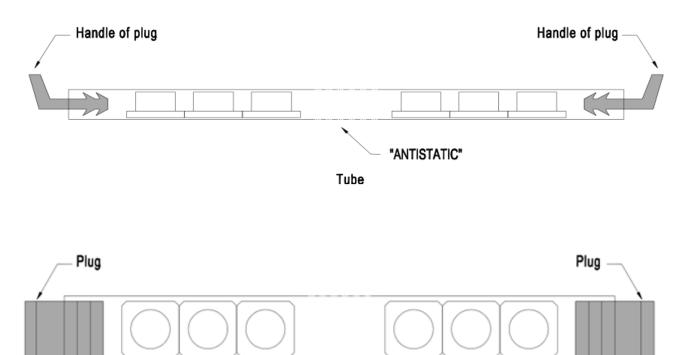




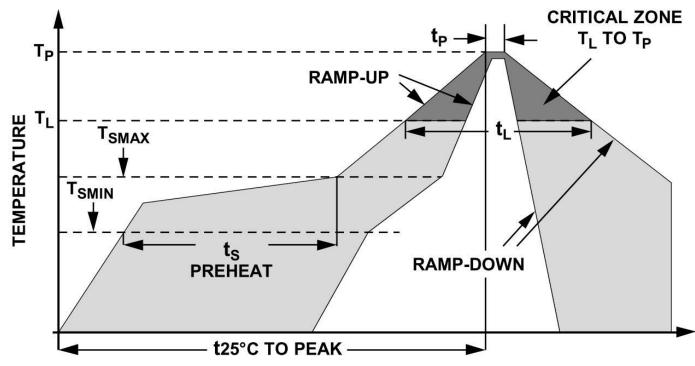




• Shipping Package







• Soldering recommendation

TIME

Recommended Soldering Profile

Profile Feature	Pb-Free
Average ramp-up rate(TsMax to TP)	3°C/sec max.
Preheat:	
-Temperature Min.(TsMin)	150°C
-Temperature Max.(TxMax)	200°C
-Time.(TsMin to TsMax)(Ts)	60 sec to 180 sec
Time maintained above:	
-Temperature(TL)	217°C
-Time(tL)	60 sec to 150 sec
Peak temperature(TP)	260°C
Time within 5°C of actual peak temperature(TP)	20 sec to 40 sec
Ramp-down rate	4°C/sec max.
Time 25°C to peak temperature	8minutes max.